SP	FC	IFI	CAT	NS
JГ			CAI	IVO

CUSTOMER		PTC	
SAMPLE CODE (Ver.)	:		
MASS PRODUCTION CODE (Ver.)		PC2402LRS-ANH-B-Q(VER.0)	

PC-95012(

DRAWING NO (Var)

Customer Approved

Date:

Approved	QC Confirmed	Designer
18 00		郭颖颖/18-36

- Approval For Specifications Only.
 - * This specification is subject to change without notice.

Please contact Powertip or it's representative before designing your product based on this specification.

Approval For Specifications and Sample.

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RECORDS OF REVISION

Date	Rev.	Description	Note	Page
2006/01/12	0	PC2402LRS-ANH-B-Qis the ROHS compliant part number based on Powertip's standard PC2402LRS-ANH-B		

Total: 20Page



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Note: For detailed information please refer to IC data sheet: NT3881,KS0063B



1. SPECIFICATIONS

1.1 Features

Item	Standard Value		
Display Type	24*2 Characters		
LCD Type	STN Gray Positive Transflective Normal Temp.		
Driver Condition	LCD Module: 1/16 Duty, 1/4 Bias		
Viewing Direction	6 O'clock		
Backlight	YG LED B/L		
Weight	54 g		
Interface	_		
Other	_		

1.2 Mechanical Specifications

Item	Item Standard Value	
Outline Dimension	118.0 (L) * 36.0 (w) * 13.8(H)(Max)	mm
Viewing Area	93.5 (L) * 15.8 (w)	mm
Active Area	88.3 (L) * 11.5 (w)	mm
Dot Size	0.6 (L) * 0.65 (w)	mm
Dot Pitch	0.65(L) * 0.7 (w)	mm

Note: For detailed information please refer to LCM drawing

1.3 Absolute Maximum Ratings

Item	Symbol	Condition	Min.	Max.	Unit
Power Supply Voltage	$V_{ m DD}$	_	-0.3	7.0	V
LCD Driver Supply Voltage	V_{LCD}	_	VDD-13.5	V _{DD} +0.3	V
Input Voltage	V_{IN}	_	-0.3	V _{DD} +0.3	V
Operating Temperature	T_{OP}	Excluded B/L	0	50	$^{\circ}\mathbb{C}$
Storage Temperature	T_{ST}	Excluded B/L	-20	70	$^{\circ}\!\mathbb{C}$
Storage Humidity	H_{D}	Ta < 40 °C	-	90	%RH



1.4 DC Electrical Characteristics

 V_{DD} = 5.0 V ± 10% , V_{SS} = 0V , Ta = 25°C

Item	Symbol	Condition	Min.	Туре	Max.	Unit
Logic Supply Voltage	$ m V_{DD}$	_	4.5	5.0	5.5	V
"H" Input Voltage	V_{IH}	_	2.2	-	V _{DD}	V
"L" Input Voltage	$V_{\rm IL}$	_	-0.3	-	0.8	V
"H" Output Voltage	V_{OH}	_	2.4	-	-	V
"L" Output Voltage	V_{OL}	_	-	-	0.4	V
Supply Current	I_{DD}	$V_{DD} = 5.0 \text{ V}$	-	2.0	3.0	mA
		0℃	-	-	-	
LCM Driver Voltage	$ m V_{OP}$	25°C*1	3.6	3.8	4.0	V
		50°C	-	-	-	

Note: *1. THE V_{OP} TEST POINT IS V_{DD} - V_{O} .

1.5 Optical Characteristics

LCD Panel: 1/16 Duty \cdot 1/5 Bias \cdot $V_{LCD} = 4.8V$ \cdot Ta = 25° C

Item	Symbol	Conditions	Min.	Тур.	Max.	Reference
View Angle	θ	$C \ge 2.0, \varnothing = 0^{\circ}$	60°	-	-	Notes 1 & 2
Contrast Ratio	С	$\theta = 5^{\circ}, \varnothing = 0^{\circ}$	4	5	-	Note 3
Response Time(rise)	tr	$\theta = 5^{\circ}, \varnothing = 0^{\circ}$	-	200ms	300ms	Note 4
Response Time(fall)/	tf	$\theta = 5^{\circ}, \varnothing = 0^{\circ}$	-	200 ms	300ms	Note 4



Note 1: Definition of angles θ and \emptyset

Light (when reflected) $z (\theta=0^{\circ})$

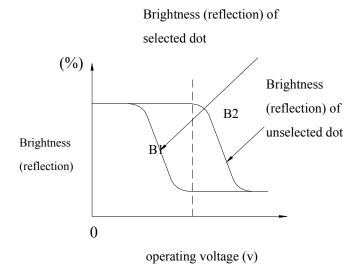
Light (when transmitted) $Y(\varnothing=0^{\circ})$ $(\theta=90^{\circ})$

Note 3: Definition of contrast C

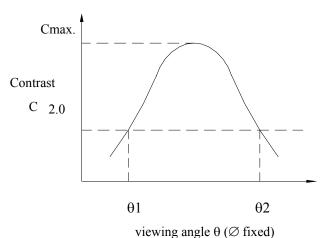
C = -

Brightness (reflection) of unselected dot (B2)

Brightness (reflection) of selected dot (B1)

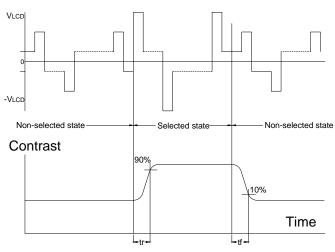


Note 2: Definition of viewing angles $\theta 1$ and $\theta 2$



Note: Optimum viewing angle with the naked eye and viewing angle θ at Cmax. Above are not always the same

Note 4: Definition of response time



Note: Measured with a transmissive LCD panel which is displayed 1 cm²

$$\begin{split} V_{LCD} : Operating \ voltage & f_{FRM} : Frame \ frequency \\ t_r & : Response \ time \ (rise) & t_f : Response \ time \ (fall) \end{split}$$



1.6 Backlight Characteristics

LCD Module with LED Backlight

Maximum Ratings

Item	Symbol	Conditions	Min.	Max.	Unit
Forward Current	IF	Ta =25°℃	-	375	mA
Reverse Voltage	VR	Ta =25°℃	-	10	V
Power Dissipation	PO	Ta =25°℃	-	1.73	W
Operating Temperature	T_{OP}	-	-20	70	$^{\circ}\!\mathbb{C}$
Storage Temperature	T_{ST}	-	-30	80	$^{\circ}\!\mathbb{C}$

Electrical / Optical Characteristics

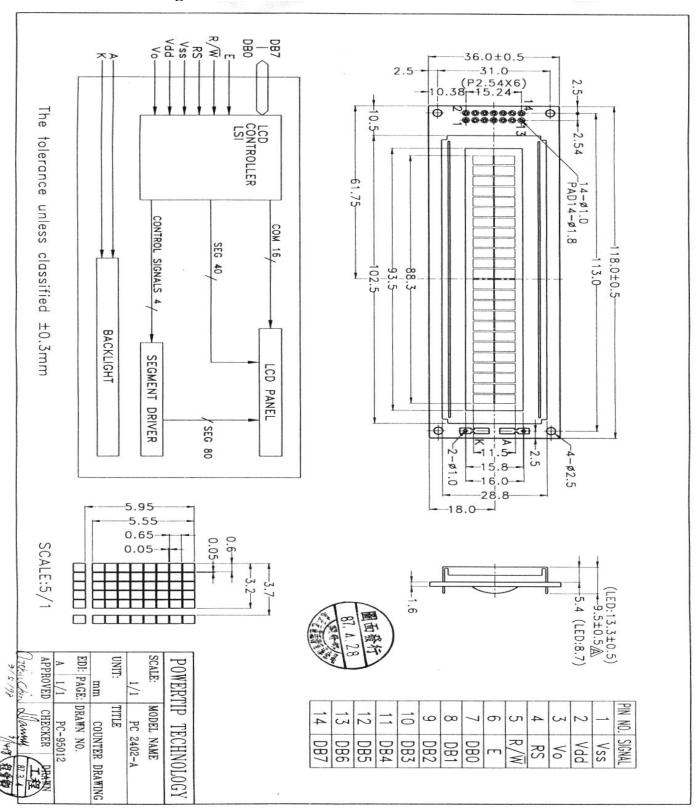
Ta =25°C

Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Voltage	VF	IF=150 mA	-	4.2	4.6	V
Reverse Current	IR	VR=10V	-	-	0.15	mA
Wavelength	λр	IF=150 mA	569	-	576	nm
Luminous Intensity (without LCD)	IV	IF=150 mA	136	170	-	cd/m ²
Color	Yellow-green					



2. MODULE STRUCTURE

2.1 Counter Drawing

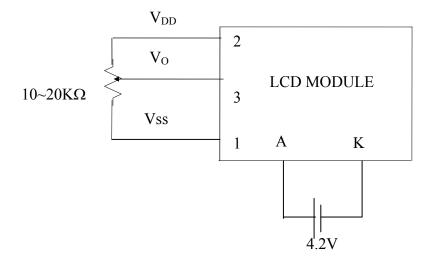




2.2 Interface Pin Description

Pin No.	Symbol	Signal Description
1	$ m V_{SS}$	Power Supply (Vss=0)
2	$V_{ m DD}$	Power Supply (V _{DD} >V _{SS})
3	V_{O}	Operating voltage for LCD
		Register Selection input
4	RS	High = Data register
4	KS	Low = Instruction register (for write)
		Busy flag address counter (for read)
		Read/Write signal input is used to select the read/write
5	R/\overline{W}	mode
		High = Read mode, Low = Write mode
6	Е	Start enable signal to read or write the data
		Four low order bi-directional three-state data bus lines. Use
7~10	$DB0 \sim DB3$	for data transfer between the MPU and the LCD module.
		These four are not used during 4-bit operation.
		Four high order bi-directional three-state data bus lines.
11~14	DB4 ~ DB7	Used for data transfer between the MPU and the LCD
11~14	DB4 ~ DB/	module.
		DB7 can be used as a busy flag.
	A	Power supply for LED B/L(+)
	K	Power supply for LED B/L(-)

Contrast Adjust

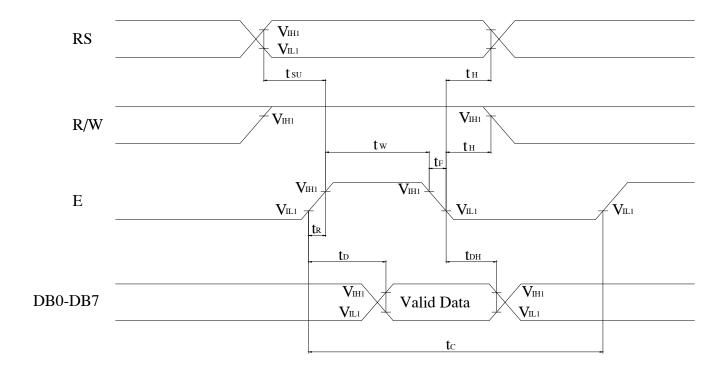


+

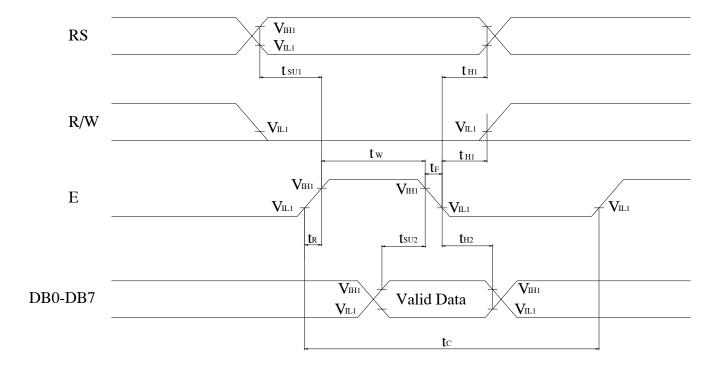


2.3 Timing Characteristics

• Read cycle



• Write cycle





• Read cycle

VDD=5.0V±10%,VSS=0V,Ta=25°C

Characteristics	Symbol	Condition	Min.	Type	Max.	Unit
Enable cycle time	$t_{ m cyCE}$	-	500	-	-	ns
Enable "H" level pulse width	$t_{ m WEH}$	-	300	-	-	ns
Enable rise/fall time	$t_{rE,} t_{fE}$	-	-	-	25	ns
RS,R/W setup time	t_{AS}	-	60 ¹	-	-	ns
			100^{2}			
RS,R/W address hold time	t_{AH}	-	10	-	-	ns
Read data output delay	t_{RD}	$C_L=100pF$	-	-	190	ns
Read data hold time	t_{DHR}		20	-	-	ns

• Write cycle

Characteristics	Symbol	Condition	Min.	Type	Max.	Unit
Enable cycle time	$t_{ m cycE}$	-	500	-	-	ns
Enable "H" level pulse width	$t_{ m WEH}$	-	300	-	-	ns
Enable rise/fall time	$t_{rE,} t_{fE}$	-	-	-	25	ns
$RS,R/\overline{W}$ setup time	t_{AS}	-	60 ¹	-	-	ns
			100^{2}			
RS,R/W address hold time	t_{AH}	-	10	-	-	ns
Data setup time	$t_{ m DS}$	-	100	-	-	ns
Write data hold time	t_{DH}	-	10	-	-	ns

Notes: 1: 8-bit operation mode

2: 4-bit operation mode

2.4 Display Command



					Instru	iction	Code	:				Execution Time(max)
Instructions											Description	(f _{osc} =
	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0		250KHZ)
Clear	0	0	0	0	0	0	0	0	0	1	Clear entire display area, restore	1.64ms
Display											display from shift, and load	
											address counter with DD RAM	
											address 00H	
Display/	0	0	0	0	0	0	0	0	1	×	Restore display from shift and	1.64ms
Cursor Home											load address counter with DD	
											RAM address00H	
Entry Mode	0	0	0	0	0	0	0	1	I/D	S	Specify direction of cursor	40µs
Set											movement and display shift mode.	
											This operation takes place after	
											each data transfer(read/write)	
Display	0	0	0	0	0	0	1	D	C	В	Specify activation of display (D)	40µs
ON/OFF											cursor (C) and blinking of	
Control											character at cursor position (B).	
Display/	0	0	0	0	0	1	S/C	R/L	×	×	Shift display or move cursor.	40µs
Cursor Shift												
Function Set	0	0	0	0	1	DL	N	F	X	X	Set interface data length (D),	40µs
											number of display line (N), and	
											character font (F).	
RAM Address	0	0	0	1							Load the address counter with a	40µs
Set							A(CG			CG RAM address. Subsequent	
Set											data access is for CG RAM data.	
DD RAM	0	0	1								Load the address counter with a	40µs
Address Set					ADD			DD RAM address. Subsequent				
Address Set											data access is for DD RAM data.	
Busy	0	1									Read Busy Flag (BF) and contents	40µs
Flag/Address						1	AC				of Address Counter (AC).	
Counter Read												
CG RAM/DD	1	0									Write data to CG RAM or DD	40µs
RAM Data						Wri	te data	a			RAM.	
Write												



CG RAM/DD	1	1		Read data from CG RAM or DD	40µs
RAM Data			Read data	RAM	
Read					

Note 1: Symbol "*" signifies an insignificant bit (disregards).

Note 2:Correct input value for "N" is predetermined for each model.

2.5 Character Pattern



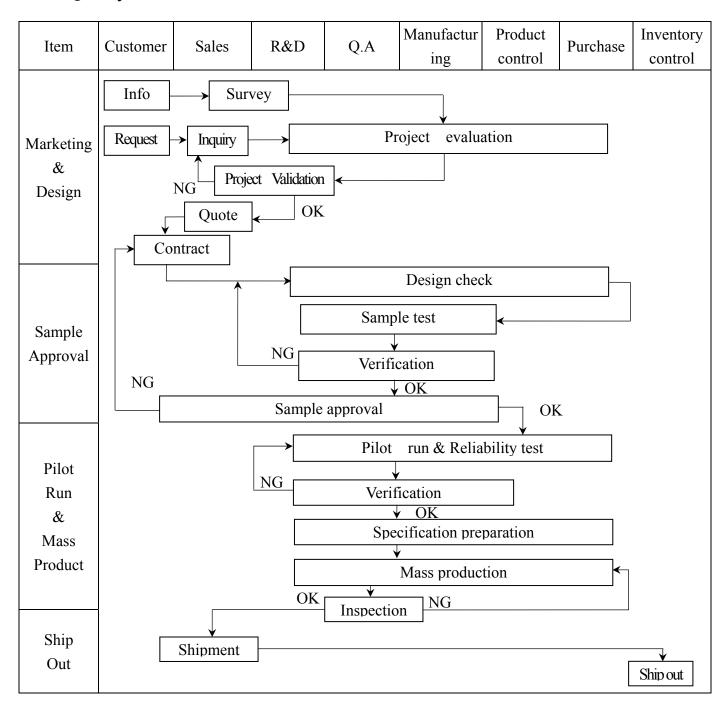
■ CHARACTER PATTERN(SO/HO/EA,WA)

Lower 4 Bits	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
xxxx0000	CG RAM (1)					====		 -					-:::	≡.	F	
xxxx0001	(2)		i	1			-===	-:::			===			;	-:::	
xxxx0010	(3)		11					 -			! "		! !.!	_::: [*]		
xxxx0011	(4)		#	:	 :	=====	:	:==-			!		-==-	===	==:-	=:-:=
xxxx0100	(5)		:	∷ ‡.			=:::	ŧ				: <u>:</u> ::	j	-	 	
xxxx0101	(6)		::- <u>:</u> :	====		<u> </u>	::::	II			==		:-!- -		=:::	
xxxx0110	(7)			<u>:::</u> :	!	l .l		ii			====	17		===	:	
xxxx0111	(8)		:=			<u>[,,]</u>	-==	I,ı,I			-;::	=	::::			H
xxxx1000	(1)		=			: ::;	! :	<u>_</u> :-:_			j-	-:::]	:#:	i_i	.,i	:-:
xxxx1001	(2)].i		I	!- _! .!	i	•::::		-		· <u>`</u> [<u>.</u> .i	ı İ.	:	·]
****1010	(3)		: -[-:	##	!	====	:						-	i		====
xxxx1011	(4)		[:	! :::		-:-	-			:= ! -	<u>.</u> :	 -		:-:	
xxxx1100	(5)		:=	-:-	!	4		i			-[-:-	∷. .₌	·I	<u></u>	:::	===
xxxx1101	(6)				i-i		[**]]- -		-		:		 	: ::	
xx xx1110	(7)				 	- -	 -	-::-		1					i	
xxxx1111	(8)			:-			::	-15			- 1.1	!	:		====	

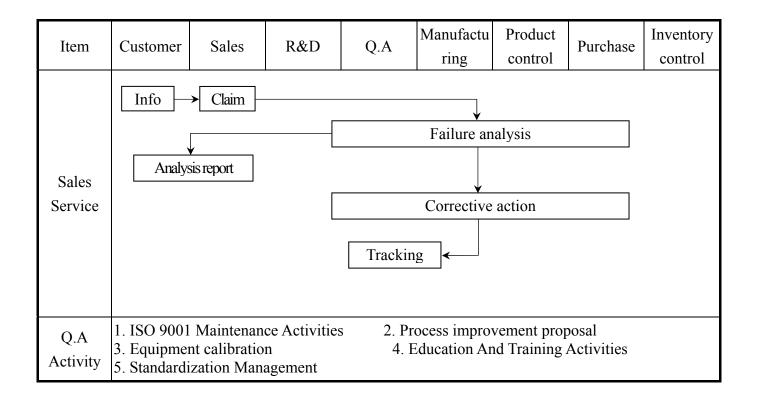
3. QUALITY ASSURANCE SYSTEM



3.1 Quality Assurance Flow Chart









3.2 Inspection Specification

Inspection Standard: MIL-STD-105E Table Normal Inspection Single Sampling Level II •

Equipment: Gauge · MIL-STD · Powertip Tester · Sample ·

IQC Defect Level: Major Defect AQL 0.4; Minor Defect AQL 1.5 °

FQC Defect Level: 100% Inspection • OUT Going Defect Level: Sampling •

Specification:

NO	Item	Specification	Judge	Level	
1	Part Number	The part number is inconsistent with work order of production	N.G.	Major	
2	Quantity	The quantity is inconsistent with work order of production	N.G.	Major	
	Electronic	The display lacks of some patterns.	N.G.	Major	
	characteristics of	Missing line.	N.G.	Major	
3	LCM	The size of missing dot, A is $> 1/2$ Dot size	N.G.	Major	
	$A=(L+W)\div 2$	There is no function.	N.G.	Major	
		Output data is error	N.G.	Major	
		Material is different with work order of production	N.G.	Major	
		LCD is assembled in inverse direction	N.G.	Major	
		Bezel is assembled in inverse direction	N.G.	Major	
		Shadow is within LCD viewing area + 0.5 mm	N.G.	Major	
	Appearance of	The diameter of dirty particle, A is > 0.4 mm	N.G.	Minor	
	LCD A=(L+W)÷2	Dirty particle length is $>$ 3.0mm, and 0.01mm $<$ width \leq 0.05mm	N.G.	Minor	
4		Display is without protective film	N.G.	Minor	
	Dirty particle	Conductive rubber is over bezel 1mm	N.G.	Minor	
	(Including	Polarizer exceeds over viewing area of LCD	N.G.	Minor	
	scratch · bubble)	Area of bubble in polarizer, A > 1.0mm, the number of			
		bubble is >1 piece.	N.G.	Minor	
		0.4mm < Area of bubble in polarizer, A < 1.0mm, the	N.G.	Minor	
		number of bubble is >4 pieces.			
		Burned area or wrong part number is on PCB	N.G.	Major	
		The symbol, character, and mark of PCB are unidentifiable.	N.G	Minor	
		The stripped solder mask, A is > 1.0mm	N.G.	Minor	
		0.3mm < stripped solder mask or visible circuit, A <	N. C.	3.6	
_	Appearance of	1.0mm, and the number is ≥ 4 pieces	N.G.	Minor	
5	PCB	There is particle between the circuits in solder mask	N.G	Minor	
	$A=(L+W)\div 2$	The circuit is peeled off or cracked	N.G	Minor	
		There is any circuits risen or exposed.	N.G	Minor	
		0.2 mm $<$ Area of solder ball, A is ≤ 0.4 mm	N.G		
		The number of solder ball is ≥ 3 pieces		Minor	
		The magnitude of solder ball, A is > 0.4 mm.	N.G	Minor	



NO	Item	Specification	Judge	Level
		The shape of modeling is deformed by touching.	N.G.	Major
	Appearance of	Insufficient epoxy: Circuit or pad of IC is visible	N.G.	Minor
6	molding A=(L+W)÷2	Excessive epoxy: Diameter of modeling is >20mm or height is >2.5mm	N.G.	Minor
		The diameter of pinhole in modeling, A is >0.2mm.	N.G.	Minor
		The folding angle of frame must be $>45^{\circ} +10^{\circ}$	N.G.	Minor
7	Appearance of frame	The area of stripped electroplate in top-view of frame, A is > 1.0mm.	N.G.	Minor
/	$A=(L+W)\div 2$	Rust or crack is (Top view only)	N.G.	Minor
		The scratched width of frame is >0.06mm. (Top view only)	N.G.	Minor
	T1 4 1	The color of backlight is nonconforming	N.G.	Major
	Electrical characteristic of	Backlight can't work normally.	N.G.	Major
8	backlight	The LED lamp can't work normally	N.G.	Major
8	A=(L+W)÷2	The unsoldering area of pin for backlight, A is $> 1/2$ solder joint area.	N.G.	Minor
	A-(L+W).2	The height of solder pin for backlight is >2.0mm	N.G.	Minor
		The mark or polarity of component is unidentifiable.	N.G.	Minor
		The height between bottom of component and surface of the PCB is floating > 0.7mm	N.G.	Minor
10	Assembly parts A=(L+W)÷2	D>1/4W W D D D Pad	N.G.	Minor
	11 (2 · 11).2	End solder joint width, D' is >50% width of component termination or width of pad	N.G.	Minor
		Side overhang, D is >25% width of component termination.	N.G.	Minor
		Component is cracked, deformed, and burned, etc.	N.G.	Minor
		The polarity of component is placed in inverse direction.	N.G.	Minor
		Maximum fillet height of solder extends onto the component body or minimum fillet height is <0.5mm.	N.G.	Minor



4. RELIABILITY TEST

4.1 Reliability Test Condition

NO	Item	Test Condition						
1	High Temperature Storage	Storage at 70 ±2°C 96~100 hrs Surrounding temperature, then storage at normal condition 4hrs						
2	Low Temperature Storage	Storage at -20 ±2°C 96~100 hrs Surrounding temperature, then storage at normal condition 4hrs						
3	High Temperature /Humidity Storage	1.Storage 96~100 hrs 60±2°C, 90~95%RH surrounding temperature, then storage at normal condition 4hrs. (Excluding the polarizer). or 2.Storage 96~100 hrs 40±2°C, 90~95%RH surrounding temperature, then storage at normal condition 4 hrs.						
4	Temperature Cycling	$-20^{\circ}\text{C} \rightarrow 25^{\circ}\text{C} \rightarrow 70^{\circ}\text{C} \rightarrow 25^{\circ}\text{C}$ $(30\text{mins}) (5\text{mins}) (30\text{mins}) (5\text{mins})$ 10 Cycle						
5	Vibration	10~55Hz (1 minute) 1.5mm X,Y and Z direction * (each 2hrs)						
6	ESD Test	Air Discharge: Apply 6 KV with 5 times discharge for each polarity +/- Testing location: Around the face of LCD	Contact Discharge: Apply 250V with 5 times discharge for each polarity +/- Testing location: 1.Apply to bezel. 2.Apply to Vdd, Vss.					
7	Drop Test	Packing Weight (Kg) $0 \sim 45.4$ $45.4 \sim 90.8$ $90.8 \sim 454$ Over 454	Drop Height (cm) 122 76 61 46					



5. PRECAUTION RELATING PRODUCT HANDLING

5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module, be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So, please handle it very carefully, do not touch, push or rub the exposed polarizing with anything harder than an HB pencil lead (glass, tweezers, etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands, this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is 320±10°C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM.

5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is 25° C $\pm 5^{\circ}$ C and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush, shake, or jolt the module.

5.4 TERMS OF WARRANTY

5.4.1 Applicable warrant period

The period is within thirteen months since the date of shipping out under normal using and storage conditions.

5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.